MA3SE02

Silicon epitaxial planar type

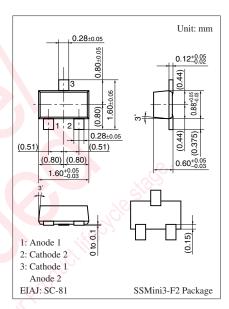
For cellular phone

■ Features

- High-frequency wave detection is possible
- ullet Low forward voltage V_F
- Small terminal capacitance C_t

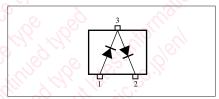
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		V _R	20	V	
Maximum peak reverse voltage		V_{RM}	20	V	
Forward current	Single	I_{F}	35	mA	
	Series		25		
Peak forward	Single	I_{FM}	100	mA	
current	Series		70		
Junction temperature		T _j	125	°C	
Storage temperature		T _{stg}	-55 to +125	°C/O	



Marking Symbol: M6B

Internal Connection

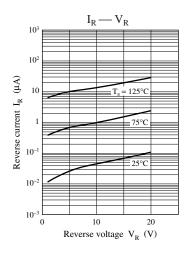


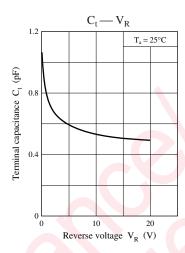
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 1 \text{ mA}$		0.40	V
	V_{F2}	I _F = 35 mA		1.0	
Reverse current	I_R	V _R = 15 V		200	nA
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$		1.2	pF
Forward dynamic resistance	$r_{\rm f}$	I _F = 5 mA	9		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz





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